

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Sharon N. Farrens et al.

Application No.:

Filed:

For: IN SITU PLASMA WAFER
BONDING METHOD

Customer No.: 20350

Confirmation No.:

Examiner: Evan T. Pert

Technology Center/Art Unit: 2829

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Prior to examination of the above-referenced application, please enter the following amendments and remarks:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 7 of this paper.